PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jae Hak Kim	09/01/2006

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.
Street Address:	416 Maetan-dong, Yeongtong-gu
Internal Address:	Suwon-si
City:	Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11470320

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	7649-17
NAME OF SUBMITTER:	Candi L. Riggs

Total Attachments: 2
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CH $40.00 11470320

Attorney Docket No. 7649-17

ASSIGNMENT

THIS ASSIGNMENT, made by me, **Jaehak Kim**, a citizen of the Republic of Korea, residing at 1520 Max Way, Fishkill, New York 12524, USA;

WITNESSETH: That,

WHEREAS, I am an inventor of certain new and useful improvements in **METHODS OF FORMING DUAL-DAMASCENE INTERCONNECT STRUCTURES USING ADHESION LAYERS HAVING HIGH INTERNAL COMPRESSIVE STRESS AND STRUCTURES FORMED THEREBY**, for which an application has been filed, or is being concurrently filed, in the United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 11/470,320, filed 09/06/2006) the filing date and application number of said application when known or to file this Assignment concurrently with the application; and

WHEREAS, **Samsung Electronics Co., Ltd.**, a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring my entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer, and convey unto the said assignee, its successors and assigns, my entire right, title, and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues or other forms of protection thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted along with any term extensions thereon or therefor, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

DECLARATION AND POWER OF ATTORNEY – CONTINUED

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Full name of first joint inventor: **Jaehak Kim**

Inventor's Signature: Jaehak Kim Date: 09-01-2006

Residence: Fishkill, New York

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